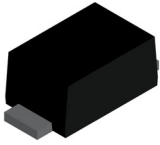
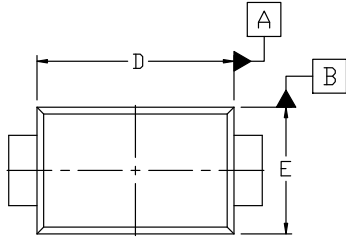


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

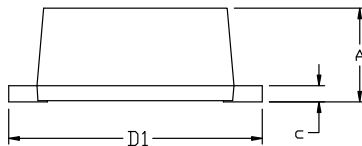


**SOD-123FA**  
**CASE 425AB**  
**ISSUE A**

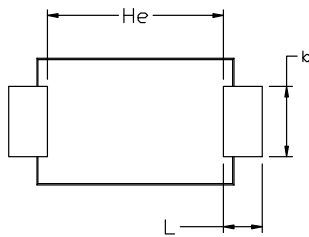
DATE 11 AUG 2022



TOP VIEW



FRONT VIEW

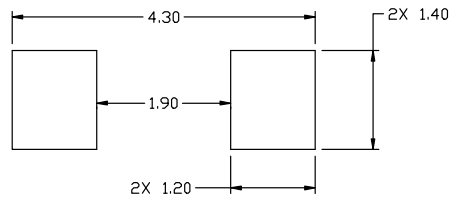


BOTTOM VIEW

NOTES:

1. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND THE BAR PROTRUSIONS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	1.23	1.33	1.43
b	0.80	1.00	1.20
c	0.16	0.23	0.30
D	2.70	2.80	2.90
D1	3.40	3.60	3.80
E	1.70	1.80	1.90
He	2.45	---	2.60
L	0.35	0.60	0.85



**RECOMMENDED MOUNTING FOOTPRINT\***

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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